



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 09/464,322
Filing Date: December 15, 1999
Applicant: Heung-Kyu KWON et al.
Group Art Unit: 2815
Examiner: Chris C. CHU
Title: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF
FABRICATING THE SAME
Attorney Docket: 25611-000085/US

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September 14, 2006

AMENDMENT AFTER FINAL REJECTION UNDER 35 CF.R.. § 1.116

Sir:

In response to the Office Action mailed June 21, 2006, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Specification begin on page 2 of this Amendment.

Amendments to the Claims begin on page 3 of this Amendment.

Remarks begin on page 7 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
Total	18	-	20	=	0
Independent	3	-	3	=	0